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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Discontinued at Digi-Key
Core Processor	80515
Core Size	8-Bit
Speed	24MHz
Connectivity	I²C, SmartCard, UART/USART
Peripherals	LED, POR, WDT
Number of I/O	8
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 6.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VFQFN Exposed Pad
Supplier Device Package	44-QFN (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/analog-devices/73s1210f-44im-f-p

Table 5: Program Security Registers

Register	SFR Address	R/W	Description
FLSHCTL	0xB2	R/W	Bit 0 (FLSH_PWE): Program Write Enable: 0 – MOVX commands refer to XRAM Space, normal operation (default). 1 – MOVX @DPTR,A moves A to Program Space (Flash) @ DPTR. This bit is automatically reset after each byte written to flash. Writes to this bit are inhibited when interrupts are enabled.
		W	Bit 1 (FLSH_MEEN): Mass Erase Enable: 0 – Mass Erase disabled (default). 1 – Mass Erase enabled. Must be re-written for each new Mass Erase cycle.
		R/W	Bit 6 (SECURE): Enables security provisions that prevent external reading of flash memory and CE program RAM. This bit is reset on chip reset and may only be set. Attempts to write zero are ignored.
TRIMPCtl	0xFFD1	W	0x54 value will set up for security fuse control. All other values are reserved and should not be used.
FUSECtl	0xFFD2	W	0xA6 value will cause the selected fuse to be blown. All other values will stop the burning process.
SECReg	0xFFD7	W	Bit 7 (PARAMSEC): 0 – Normal operation. 1 – Enable permanent programming of the security fuses.
		R	Bit 5 (SECPIN): Indicates the state of the SEC pin. The SEC pin is held low by a pull-down resistor. The user can force this pin high during boot sequence time to indicate to firmware that sec mode 1 is desired.
		R/W	Bit 1 (SECSET1): See the Program Security section.
		R/W	Bit 0 (SECSET0): See the Program Security section.

1.5 Special Function Registers (SFRs)

The 73S1210F utilizes numerous SFRs to communicate with the 73S1210Fs many peripherals. This results in the need for more SFR locations outside the direct address IRAM space (0x80 to 0xFF). While some peripherals are mapped to unused IRAM SFR locations, additional SFRs for the smart card and other peripheral functions are mapped to the top of the XRAM data space (0xFC00 to 0xFFFF).

1.5.1 Internal Data Special Function Registers (SFRs)

A map of the Special Function Registers is shown in Table 6.

Table 6: IRAM Special Function Registers Locations

Hex\Bin	X000	X001	X010	X011	X100	X101	X110	X111	Bin/ Hex
F8									FF
F0	B								F7
E8									EF
E0	A								E7
D8	BRCON								DF
D0	PSW	**KCOL**	**KROW**	**KSCAN**	**KSTAT**	**KSIZE**	**KORDERL**	**KORDERH**	D7
C8	T2CON								CF
C0	IRCON								C7
B8	IEN1	IP1	S0RELH	S1RELH					BF
B0			**FLSHCTL**					**PGADDR**	B7
A8	IEN0	IP0	S0RELL						AF
A0									A7
98	S0CON	S0BUF	IEN2	S1CON	S1BUF	S1RELL			9F
90	**USR70**	**UDIR70**	DPS		**ERASE**				97
88	TCON	TMOD	TL0	TL1	TH0	TH1		**MCLKCtl**	8F
80		SP	DPL	DPH	DPL1	DPH1	WDTREL	PCON	87

Only a few addresses are used, the others are not implemented. SFRs specific to the 73S1210F are shown in **bold** print (gray background). Any read access to unimplemented addresses will return undefined data, while most write access will have no effect. However, a few locations are reserved and not user configurable in the 73S1210F. **Writes to the unused SFR locations can affect the operation of the core and therefore must not be written to. This applies to all the SFR areas in both the IRAM and XRAM spaces. In addition, all unused bit locations within valid SFR registers must be left in their default (power on default) states.**

1.5.2 IRAM Special Function Registers (Generic 80515 SFRs)

Table 7 shows the location of the SFRs and the value they assume at reset or power-up.

Table 7: IRAM Special Function Registers Reset Values

Name	Location	Reset Value	Description
SP	0x81	0x07	Stack Pointer
DPL	0x82	0x00	Data Pointer Low 0
DPH	0x83	0x00	Data Pointer High 0
DPL1	0x84	0x00	Data Pointer Low 1
DPH1	0x85	0x00	Data Pointer High 1
WDTREL	0x86	0x00	Watchdog Timer Reload register
PCON	0x87	0x00	Power Control
TCON	0x88	0x00	Timer/Counter Control
TMOD	0x89	0x00	Timer Mode Control
TL0	0x8A	0x00	Timer 0, low byte
TL1	0x8B	0x00	Timer 1, high byte
TH0	0x8C	0x00	Timer 0, low byte
TH1	0x8D	0x00	Timer 1, high byte
MCLKCtl	0x8F	0x0A	Master Clock Control
USR70	0x90	0xFF	User Port Data (7:0)
UDIR70	0x91	0xFF	User Port Direction (7:0)
DPS	0x92	0x00	Data Pointer Select Register
ERASE	0x94	0x00	Flash Erase
S0CON	0x98	0x00	Serial Port 0, Control Register
S0BUF	0x99	0x00	Serial Port 0, Data Buffer
IEN2	0x9A	0x00	Interrupt Enable Register 2
S1CON	0x9B	0x00	Serial Port 1, Control Register
S1BUF	0x9C	0x00	Serial Port 1, Data Buffer
S1RELL	0x9D	0x00	Serial Port 1, Reload Register, low byte
IEN0	0xA8	0x00	Interrupt Enable Register 0
IP0	0xA9	0x00	Interrupt Priority Register 0
S0RELL	0xAA	0xD9	Serial Port 0, Reload Register, low byte
FLSHCTL	0xB2	0x00	Flash Control
PGADDR	0xB7	0x00	Flash Page Address
IEN1	0xB8	0x00	Interrupt Enable Register 1
IP1	0xB9	0x00	Interrupt Priority Register 1
S0RELH	0xBA	0x03	Serial Port 0, Reload Register, high byte
S1RELH	0xBB	0x03	Serial Port 1, Reload Register, high byte
IRCON	0xC0	0x00	Interrupt Request Control Register
T2CON	0xC8	0x00	Timer 2 Control
PSW	0xD0	0x00	Program Status Word
KCOL	0XD1	0x1F	Keypad Column

Name	Location	Reset Value	Description
KROW	0XD2	0x3F	Keypad Row
KSCAN	0XD3	0x00	Keypad Scan Time
KSTAT	0XD4	0x00	Keypad Control/Status
KSIZE	0XD5	0x00	Keypad Size
KORDERL	0XD6	0x00	Keypad Column LS Scan Order
KORDERH	0XD7	0x00	Keypad Column MS Scan Order
BRCON	0xD8	0x00	Baud Rate Control Register (only BRCON.7 bit used)
A	0xE0	0x00	Accumulator
B	0xF0	0x00	B Register

1.5.3 External Data Special Function Registers (SFRs)

A map of the XRAM Special Function Registers is shown in Table 8. The smart card registers are listed separately in Table 107.

Table 8: XRAM Special Function Registers Reset Values

Name	Location	Reset Value	Description
DAR	0x FF80	0x00	Device Address Register (I^2C)
WDR	0x FF81	0x00	Write Data Register (I^2C)
SWDR	0x FF82	0x00	Secondary Write Data Register (I^2C)
RDR	0x FF83	0x00	Read Data Register (I^2C)
SRDR	0x FF84	0x00	Secondary Read Data Register (I^2C)
CSR	0x FF85	0x00	Control and Status Register (I^2C)
USRIntCtl1	0x FF90	0x00	External Interrupt Control 1
USRIntCtl2	0x FF91	0x00	External Interrupt Control 2
USRIntCtl3	0x FF92	0x00	External Interrupt Control 3
USRIntCtl4	0x FF93	0x00	External Interrupt Control 4
INT5Ctl	0x FF94	0x00	External Interrupt Control 5
INT6Ctl	0x FF95	0x00	External Interrupt Control 6
MPUCKCtl	0x FFA1	0x0C	MPU Clock Control
ACOMP	0x FFD0	0x00	Analog Compare Register
TRIMPCtl	0x FFD1	0x00	TRIM Pulse Control
FUSECtl	0x FFD2	0x00	FUSE Control
VDDFCtl	0x FFD4	0x00	VDDFault Control
SECReg	0x FFD7	0x00	Security Register
MISCtl0	0x FFF1	0x00	Miscellaneous Control Register 0
MISCtl1	0x FFF2	0x10	Miscellaneous Control Register 1
LEDCtl	0x FFF3	0xFF	LED Control Register

Accumulator (ACC, A): ACC is the accumulator register. Most instructions use the accumulator to hold the operand. The mnemonics for accumulator-specific instructions refer to accumulator as “A”, not ACC.

B Register: The B register is used during multiply and divide instructions. It can also be used as a scratch-pad register to hold temporary data.

Table 26: Control Bits for External Interrupts

Enable Bit	Description
EX0	Enable external interrupt 0
EX1	Enable external interrupt 1
EX2	Enable external interrupt 2
EX3	Enable external interrupt 3
EX4	Enable external interrupt 4
EX5	Enable external interrupt 5
EX6	Enable external interrupt 6

Flag Bit	Description
IE0	External interrupt 0 flag
IE1	External interrupt 1 flag
IEX2	External interrupt 2 flag
IEX3	External interrupt 3 flag
IEX4	External interrupt 4 flag
IEX5	External interrupt 5 flag
IEX6	External interrupt 6 flag

1.7.5.4 Power Down Interrupt Logic

The 73S1210F contains special interrupt logic to allow INT0 to wake up the CPU from a power down (CPU STOP) state. See the Power Control Modes section for details.

1.7.5.5 Interrupt Priority Level Structure

All interrupt sources are combined in groups, as shown in Table 27.

Table 27: Priority Level Groups

Group			
0	External interrupt 0	Serial channel 1 interrupt	
1	Timer 0 interrupt	–	External interrupt 2
2	External interrupt 1	–	External interrupt 3
3	Timer 1 interrupt	–	External interrupt 4
4	Serial channel 0 interrupt	–	External interrupt 5
5	–	–	External interrupt 6

Each group of interrupt sources can be programmed individually to one of four priority levels by setting or clearing one bit in the special function register IP0 and one in IP1. If requests of the same priority level are received simultaneously, an internal polling sequence as per Table 31 determines which request is serviced first.

IEN enable bits must be set to permit any of these interrupts to occur. Likewise, each interrupt has its own flag bit that is set by the interrupt hardware and is reset automatically by the MPU interrupt handler.

Interrupt Priority 0 Register (IP0): 0xA9 ← 0x00

Table 28: The IP0 Register

MSB LSB

–	WDTS	IP0.5	IP0.4	IP0.3	IP0.2	IP0.1	IP0.0

Note: WDTS is not used for interrupt controls.

- **Mode 3**
  The only difference between Mode 2 and Mode 3 is that in Mode 3 either internal baud rate generator or timer 1 can be use to specify baud rate.

The S0BUF register is used to read/write data to/from the serial 0 interface.

Serial Interface 0 Control Register (S0CON): 0x9B ← 0x00

Transmit and receive data are transferred via this register.

Table 38: The S0CON Register

MSB LSB

SM0	SM1	SM20	REN0	TB80	RB80	TI0	RI0

Bit	Symbol	Function
S0CON.7	SM0	These two bits set the UART0 mode:
S0CON.6	SM1	
S0CON.5	SM20	Enables the inter-processor communication feature.
S0CON.4	REN0	If set, enables serial reception. Cleared by software to disable reception.
S0CON.3	TB80	The 9th transmitted data bit in Modes 2 and 3. Set or cleared by the MPU, depending on the function it performs (parity check, multiprocessor communication etc.).
S0CON.2	RB80	In Modes 2 and 3 it is the 9th data bit received. In Mode 1, if SM20 is 0, RB80 is the stop bit. In Mode 0 this bit is not used. Must be cleared by software.
S0CON.1	TI0	Transmit interrupt flag, set by hardware after completion of a serial transfer. Must be cleared by software.
S0CON.0	RI0	Receive interrupt flag, set by hardware after completion of a serial reception. Must be cleared by software.

Mode	Description	SM0	SM1
0	N/A	0	0
1	8-bit UART	0	1
2	9-bit UART	1	0
3	9-bit UART	1	1

External Interrupt Control Register (USRIntCtl1) : 0xFF90 ← 0x00

Table 50: The USRIntCtl1 Register

MSB							LSB
–	U1IS.6	U1IS.5	U1IS.4	–	U0IS.2	U0IS.1	U0IS.0

External Interrupt Control Register (USRIntCtl2) : 0xFF91 ← 0x00

Table 51: The USRIntCtl2 Register

MSB							LSB
–	U3IS.6	U3IS.5	U3IS.4	–	U2IS.2	U2IS.1	U2IS.0

External Interrupt Control Register (USRIntCtl3) : 0xFF92 ← 0x00

Table 52: The USRIntCtl3 Register

MSB							LSB
–	U5IS.6	U5IS.5	U5IS.4	–	U4IS.2	U4IS.1	U4IS.0

External Interrupt Control Register (USRIntCtl4) : 0xFF93 ← 0x00

Table 53: The USRIntCtl4 Register

MSB							LSB
–	U7IS.6	U7IS.5	U7IS.4	–	U6IS.2	U6IS.1	U6IS.0

External Interrupt Control Register (INT6Ctl): 0xFF95 ← 0x00

Table 63: The INT6Ctl Register

MSB LSB

–	–	VFTIEN	VFTINT	I2CIEN	I2CINT	ANIEN	ANINT

Bit	Symbol	Function
INT6Ctl.7	–	
INT6Ctl.6	–	
INT6Ctl.5	VFTIEN	VDD fault interrupt enable.
INT6Ctl.4	VFTINT	VDD fault interrupt flag.
INT6Ctl.3	I2CIEN	When set = 1, the I^2C interrupt is enabled.
INT6Ctl.2	I2CINT	When set = 1, the I^2C transaction has completed. Cleared upon the start of a subsequent I^2C transaction.
INT6Ctl.1	ANIEN	Analog compare interrupt enable.
INT6Ctl.0	ANINT	Analog compare interrupt flag.

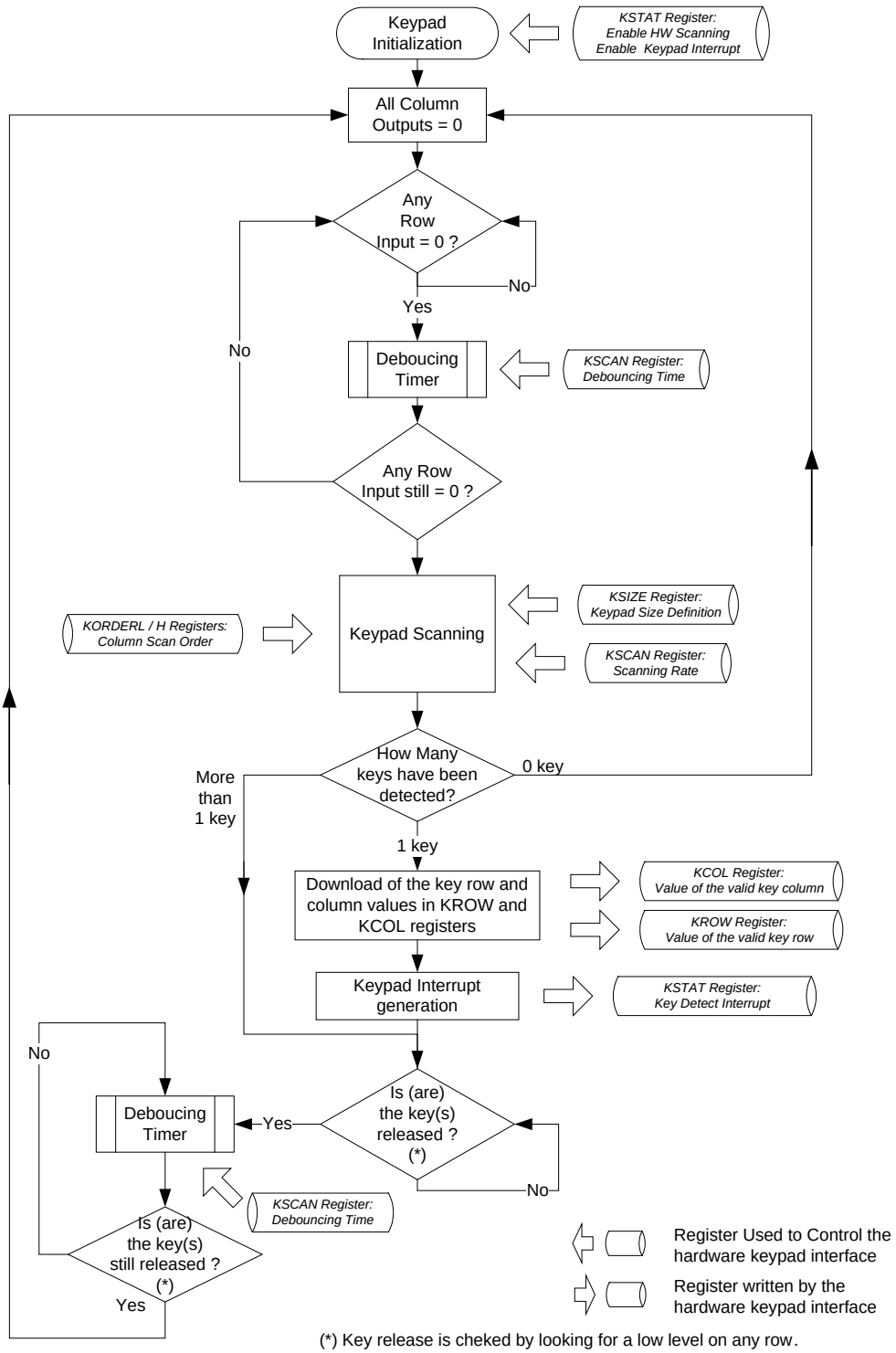


Figure 13: Keypad Interface Flow Chart

Keypad Column Register (KCOL): 0xD1 ← 0x1F

This register contains the value of the column of a key detected as valid by the hardware. In bypass mode, this register firmware writes directly this register to carry out manual scanning.

Table 64: The KCOL Register

MSB							LSB
–	–	–	COL.4	COL.3	COL.2	COL.1	COL.0

Bit	Symbol	Function
KCOL.7	–	
KCOL.6	–	
KCOL.5	–	
KCOL.4	COL.4	Drive lines bit mapped to corresponding with pins COL(4:0). When a key is detected, firmware reads this register to determine column. In bypass (S/W keyscan) mode, Firmware writes this register directly. 0x1E = COL(0) low, all others high. 0x0F = COL(4) low, all others high. 0x1F = COL(4:0) all high.
KCOL.3	COL.3	
KCOL.2	COL.2	
KCOL.1	COL.1	
KCOL.0	COL.0	

Keypad Row Register (KROW): 0xD2 ← 0x3F

This register contains the value of the row of a key detected as valid by the hardware. In bypass mode, this register firmware reads directly this register to carry out manual detection.

Table 65: The KROW Register

MSB							LSB
–	–	ROW.5	ROW.4	ROW.3	ROW.2	ROW.1	ROW.0

Bit	Symbol	Function
KROW.7	–	
KROW.6	–	
KROW.5	ROW.6	Sense lines bit mapped to correspond with pins ROW(5:0). When key detected, firmware reads this register to determine row. In bypass mode, firmware reads rows and has to determine if there was a key press or not. 0x3E = ROW(0) low, all others high. 0x1F = ROW(5) low, all others high. 0x3F = ROW(5:0) all high.
KROW.4	ROW.4	
KROW.3	ROW.3	
KROW.2	ROW.2	
KROW.1	ROW.1	
KROW.0	ROW.0	

1.7.15 Smart Card Interface Function

The 73S1210F integrates one ISO-7816 (T=0, T=1) UART, one complete ICC electrical interface as well as an external smart card interface to allow multiple smart cards to be connected using the Teridian 8010 family of interface devices. Figure 14 shows the simplified block diagram of the card circuitry (UART + interfaces), with detail of dedicated XRAM registers.

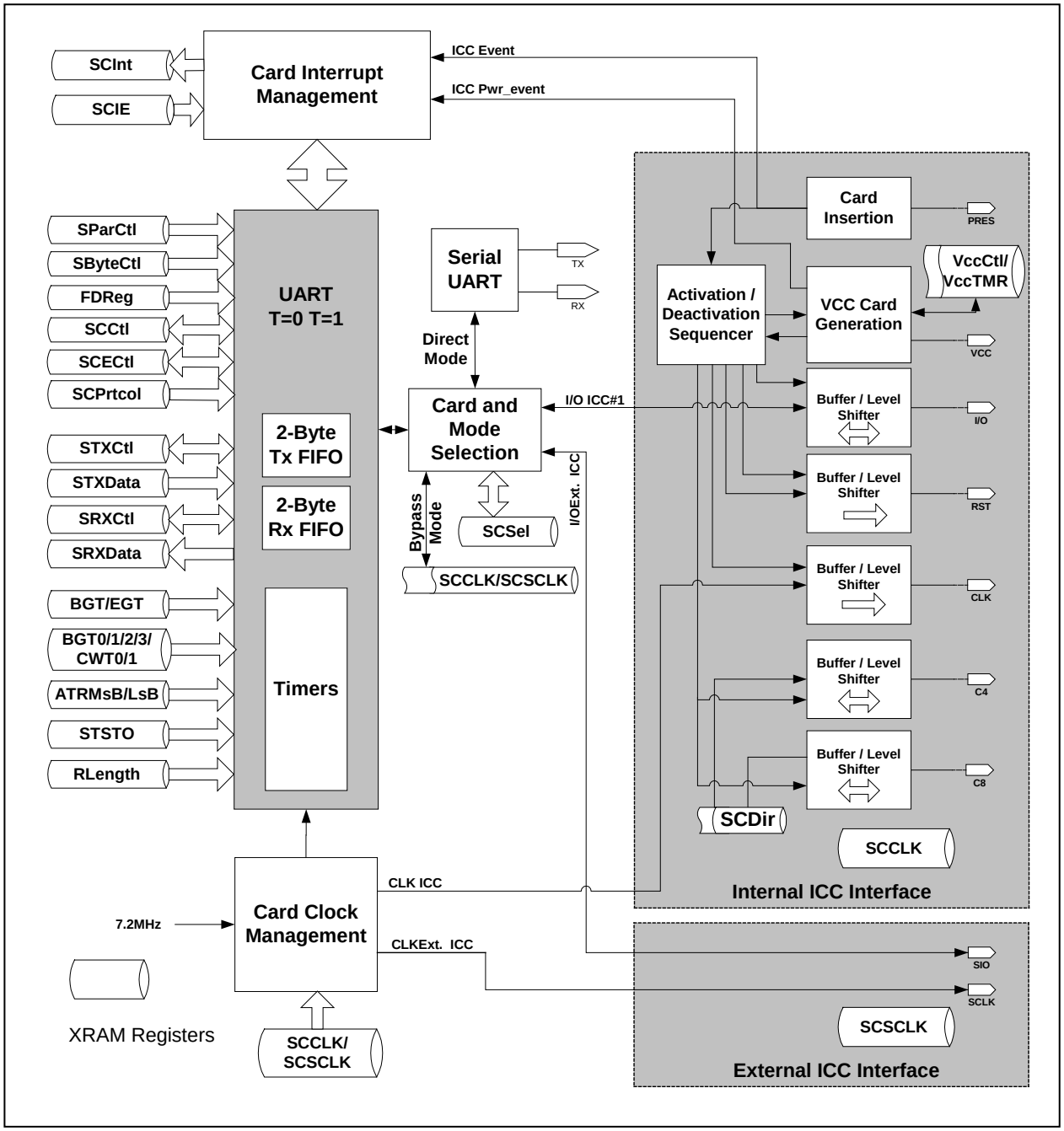
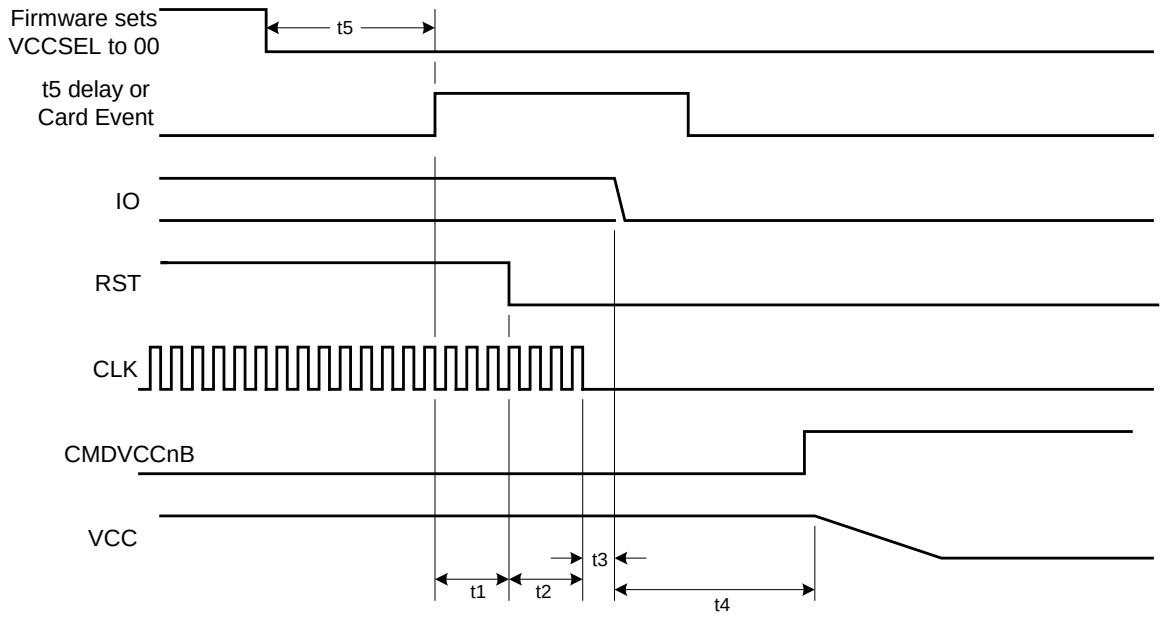


Figure 14: Smart Card Interface Block Diagram

Card interrupts are managed through two dedicated registers: SCIE (Interrupt Enable to define which interrupt is enabled) and SCInt (Interrupt status). They allow the firmware to determine the source of an interrupt, that can be a card insertion / removal, card power fault, or a transmission (TX) or reception (RX) event / fault. It should be noted that even when card clock is disabled, an ICC interrupt can be generated

Figure 16: Asynchronous Activation Sequence Timing



t1: Time after either a "card event" occurs or firmware sets the VCCSela and VCCSelb bits to 0 (see t5, VCCOff_tmr) occurs until RST is asserted low.

t2: Time after RST goes low until CLK stops.

t3: Time after CLK stops until IO goes low.

t4: Time after IO goes low until VCC is powered down.

t5: Delayed VCC off time (in ETUs per VCCOff_tmr bits). Only in effect due to firmware deactivation.

Figure 17: Deactivation Sequence

1.7.15.3 Data Reception/Transmission

When a 12Mhz crystal is used, the smart card UART will generate a 3.69Mhz (default) clock to both smart card interfaces. This will allow approximately 9600bps (1/ETU) communication during ATR (ISO 7816 default). As part of the PPS negotiation between the smart card and the reader, the firmware may determine that the smart card parameters F & D may be changed. After this negotiation, the firmware may change the ETU by writing to the SFR FDReg to adjust the ETU and CLK. The firmware may also change the smart card clock frequency by writing to the SFR SCCLK (SCECLK for external interface). Independent clock frequency control is provided to each smart card interface. Clock stop high or Clock stop low is supported in asynchronous mode. Figure 18 shows the ETU and CLK control circuits. The firmware determines when clock stop is supported by the smart card and when it is appropriate to go into that mode (and when to come out of it). The smart card UART is clocked by the same clock that is provided to the selected smart card. The transition between smart card clocks is handled in hardware to eliminate any glitches for the UART during switchover. The external smart card clock is not affected when switching the UART to communicate with the internal smart card.

Smart Card Interrupt Enable Register (SCIE): 0xFE02 ← 0x00

When set to 1, the respective condition can cause a smart card interrupt. When set to a 0, the respective condition cannot cause an interrupt. When disabled, the respective bit in the Smart Card Interrupt register can still be set, but it will not interrupt the MPU.

Table 74: The SCIE Register

MSB LSB

WTOIEN	CDEVEN	VTMREN	RXDAEN	TXEVEN	TXSNTEN	TXEREN	RXEREN

Bit	Symbol	Function
SCIE.7	WTOIEN	Wait Timeout Interrupt Enable - Enable for ATR or Wait Timeout Interrupt. In sync mode, function is RLIEN (RLen = max.) interrupt enable.
SCIE.6	CDEVEN	Card Event Interrupt Enable.
SCIE.5	VTMREN	VCC Timer Interrupt Enable.
SCIE.4	RXDAEN	Rx Data Available Interrupt Enable.
SCIE.3	TXEVEN	TX Event Interrupt Enable.
SCIE.2	TXSNTEN	TX Sent Interrupt Enable.
SCIE.1	TXEREN	TX Error Interrupt Enable.
SCIE.0	RXEREN	RX Error Interrupt Enable.

Symbol	Parameter	Condition	Min	Typ.	Max	Unit
Interface Requirements – Data Signals: I/O, AUX1 and AUX2						
V_{OH}	Output level, high	I_{OH} = 0	0.9 * V_{CC}		V_{CC}+0.1	V
		I_{OH} = -40µA	0.75 V_{CC}		V_{CC}+0.1	V
V_{OL}	Output level, low	I_{OL} = 1mA			0.15 *V_{CC}	V
V_{IH}	Input level, high		0.6 * V_{CC}		V_{CC}+0.30	V
V_{IL}	Input level, low		-0.15		0.2 * V_{CC}	V
V_{INACT}	Output voltage when outside of session	I_{OL} = 0			0.1	V
		I_{OL} = 1mA			0.3	V
I_{LEAK}	Input leakage	V_{IH} = V_{CC}			10	µA
I_{IL}	Input current, low	V_{IL} = 0			0.65	mA
I_{IL}	Input current, low	V_{IL} = 0			0.7	mA
I_{SHORTL}	Short circuit output current	For output low, shorted to V_{CC} through 33Ω			15	mA
I_{SHORTH}	Short circuit output current	For output high, shorted to ground through 33Ω			15	mA
t_R, t_F	Output rise time, fall times	For I/O, AUX1, AUX2, C_L = 80pF, 10% to 90%. For I/OUC, AUX1UC, AUX2UC, CL = 50Pf, 10% to 90%.			100	ns
t_{IR}, t_{IF}	Input rise, fall times				1	µs
R_{PU}	Internal pull-up resistor	Output stable for >200ns	8	11	14	kΩ
FD_{MAX}	Maximum data rate				1	MHz
Reset and Clock for card interface, RST, CLK						
V_{OH}	Output level, high	I_{OH} = -200µA	0.9 * V_{CC}		V_{CC}	V
V_{OL}	Output level, low	I_{OL}= 200µA	0		0.15 *V_{CC}	V
V_{INACT}	Output voltage when outside of session	I_{OL} = 0			0.1	V
		I_{OL} = 1mA			0.3	V
I_{RST_LIM}	Output current limit, RST				30	
I_{CLK_LIM}	Output current limit, CLK				70	mA
t_R, t_F	Output rise time, fall time	C_L = 35pF for CLK, 10% to 90%			8	ns
		C_L = 200pF for RST, 10% to 90%			100	ns
δ	Duty cycle for CLK	C_L = 35pF, F_{CLK} ≤ 20MHz, CLKIN duty cycle is 48% to 52%.	45		55	%

I_{DD_IN}	Supply Current – pins 28 + 40 (internal consumption – digital core)	CPU clock @ 24MHz		29	33.5	mA
		CPU clock @ 12MHz		21	24	mA
		CPU clock @ 6MHz		15.5	18	mA
		CPU clock @ 3.69MHz		13.5	15.5	mA
		Power down (-40° to 85°C)		8	50	µA
		Power down (25°C)		6	15	µA
I_{DD_OUT}	Supply Current – pin 68 (available to external circuitry)	Circuit ON			20	mA
I_{VBUS}	Supply Current from V_{BUS}	V_{CC} off, $I_{DDINTERNAL}$ < 20µA		0.2	0.4	mA
I_{VBAT} I_{VPC}	Supply Current from V_{BAT} or V_{PC}	Circuit OFF		0.01	1	µA
$VBUS_{ON}$	V_{BUS} detection threshold			3.5		V
$VBUS_{IDIS}$	V_{BUS} discharge current			50		µA
External Capacitor Values						
C_{VPC}	External filter capacitor for V_{PC}		8.0	10.0	12.0	µF
C_{VP}	External filter capacitor for V_P		2.0	4.7	10.0	µF
C_{VDD}*	External filter capacitors for V_{DD}		0.2		1.0	µF
C_{VCC}	External filter capacitor for V_{CC}	C_{VCC} should be ceramic with low ESR (<100MΩ).	0.2	0.47	1.0	µF

*Note: Recommend on 0.1µF for each V_{DD} pin.

3.8 Current Fault Detection Circuits

Symbol	Parameter	Condition	Min	Typ.	Max	Unit
IV_{Pmax}	V_P over current fault				150	mA
I_{DDmax}	VDD over-current limit		40		100	mA
I_{CCF}	Card overcurrent fault		80		150	mA
I_{CCF1P8}	Card overcurrent fault	V_{CC} = 1.8V	60		130	mA

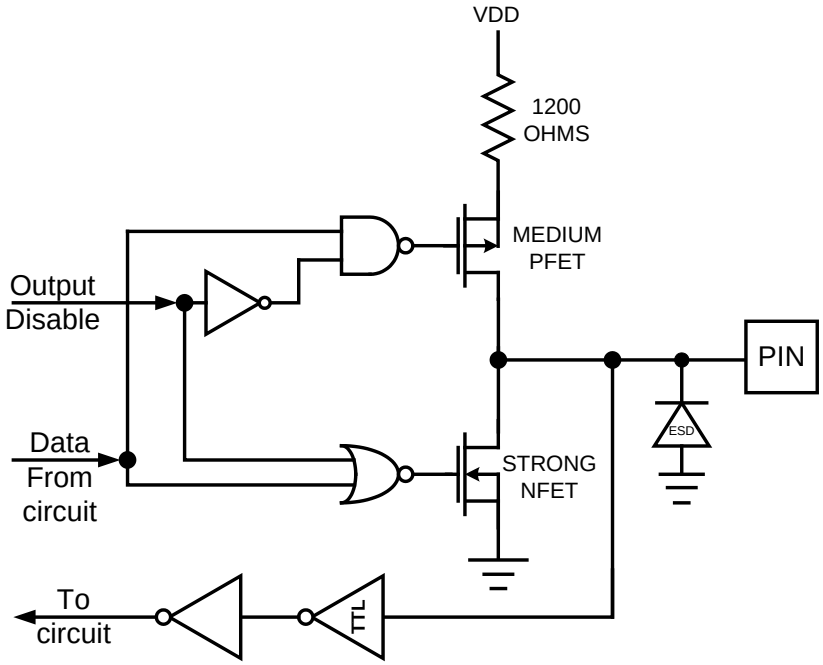


Figure 35: Keypad Column Circuit

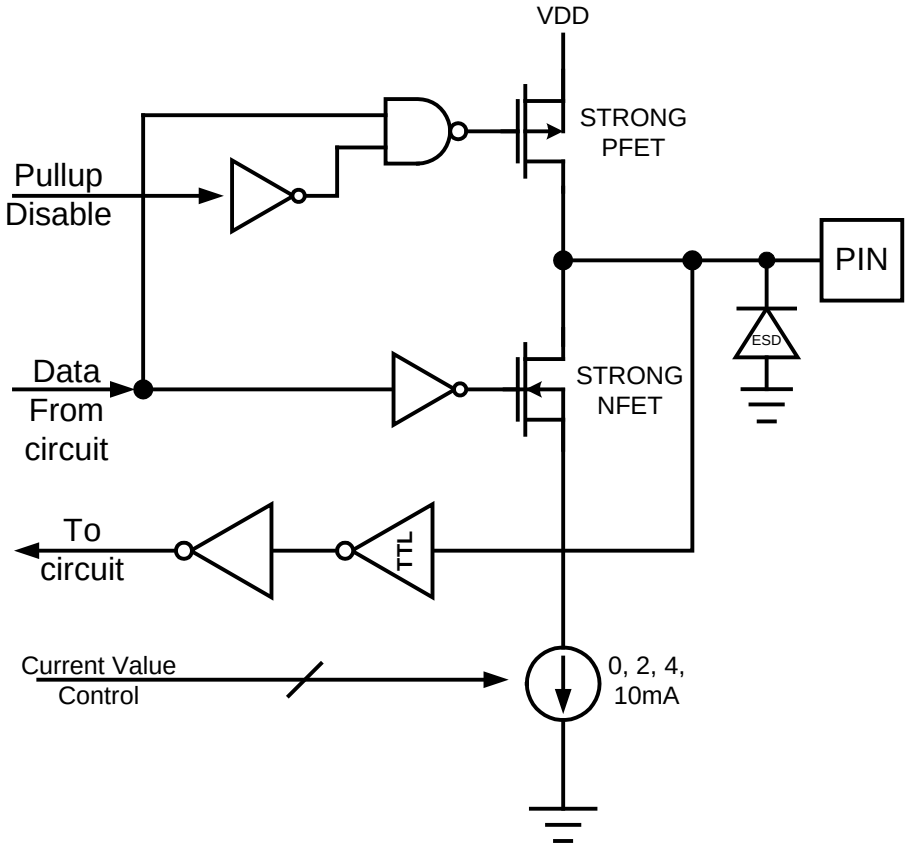


Figure 36: LED Circuit

6 Packaging Information

6.1 68-Pin QFN Package Outline

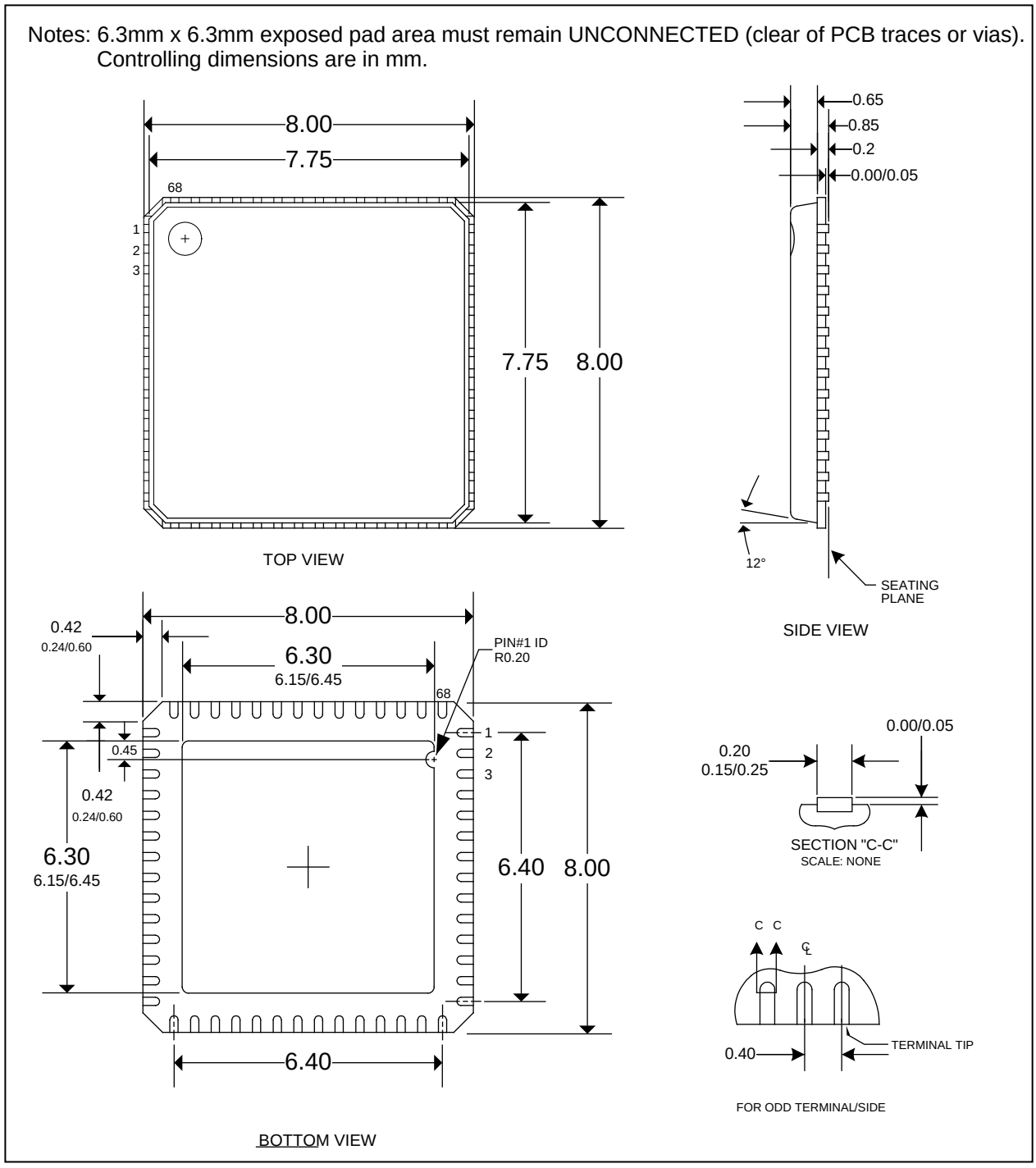


Figure 46: 73S1210F 68 QFN Mechanical Drawing

6.2 44-Pin QFN Package Outline

Notes: 5.1mm x 5.1mm exposed pad area must remain UNCONNECTED (clear of PCB traces or vias). Controlling dimensions are in mm.

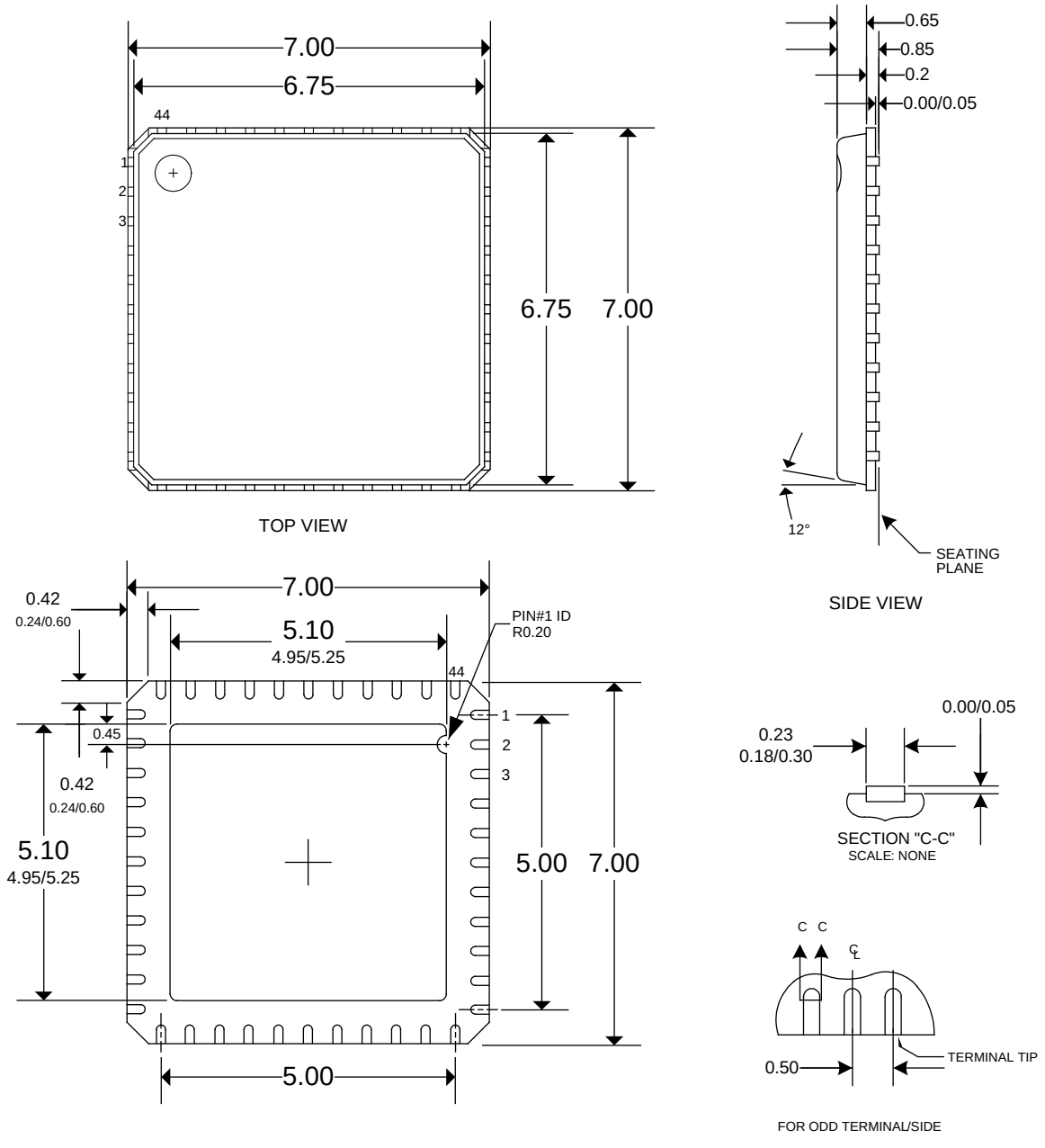


Figure 47: 73S1210F 44 QFN Package Drawing

		In Section 1.7.15.5, deleted "The ETU clock is held in reset condition until the activation sequence begins (either by VCCOK=1 or VCCTMR timeout) and will go high ½ the ETU period thereafter." In Section 1.7.15.5, added "Synchronous card operation is broken down into three primary types. These are commonly referred to as 2-wire, 3-wire and I2C synchronous cards. Each card type requires different control and timing and therefore requires different algorithms to access. Teridian has created an application note to provide detailed algorithms for each card type. Refer to the application note titled *73S12xxF Synchronous Card Design Application Note*." In Table 78 and Table 107, changed the SYCKST bit to I2CMODE. In Figure 25, replaced the schematic with a new schematic. In Section 3.4, changed the Fxtal Min from 4 to 6. Added 44-pin QFN package. Added Section 8, Related Documentation. Added Section 9, Contact Information. Formatted the document per new standard. Added section numbering.
1.3	1/22/2009	Changed the value for the I_{DD_IN} Power Down (25°C) parameter from 13 µA to 15 µA.
1.4	5/12/2009	In Table 1, corrected the 44 QFN GND pin from 37 to 26. Added the "with Programming" ordering numbers to Table 109.

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